

Machine Learning for Accelerating Atomic Layer Deposition Process Optimization

Minjong Lee, Doo San Kim, Dushyant M. Narayan, and Jiyoung Kim*

¹The University of Texas at Dallas, TX, USA

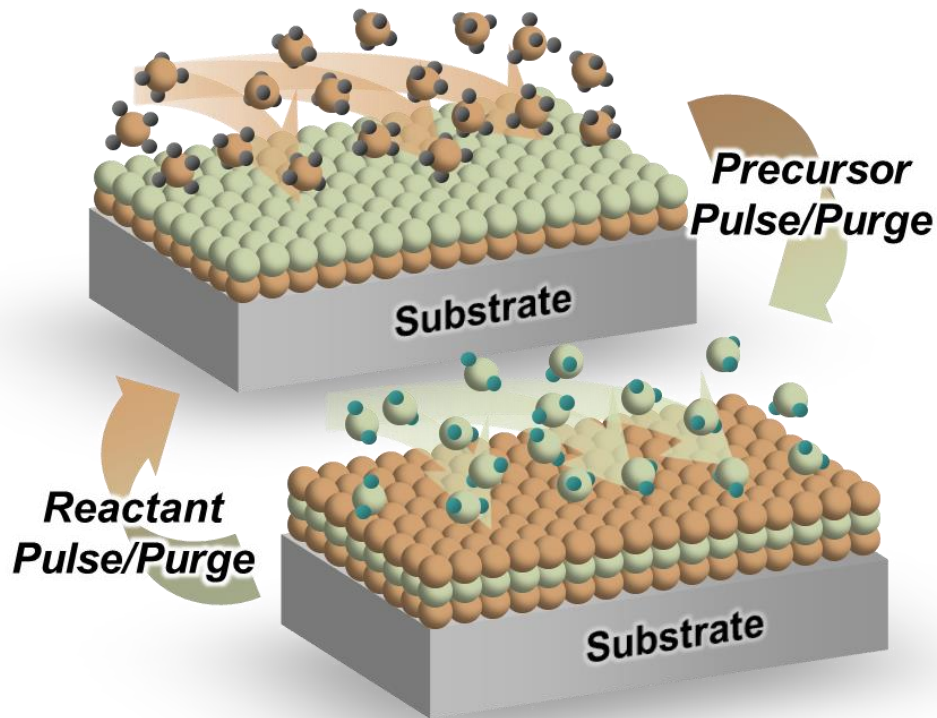
** jiyoung.kim@utdallas.edu*



Background and motivation

Atomic layer deposition (ALD)

■ Atomic Layer Deposition (ALD)



Angstrom ($\text{\AA}$)-scaled controllability

- ALD process is based on **Saturation** processes
=> **Wide process windows**

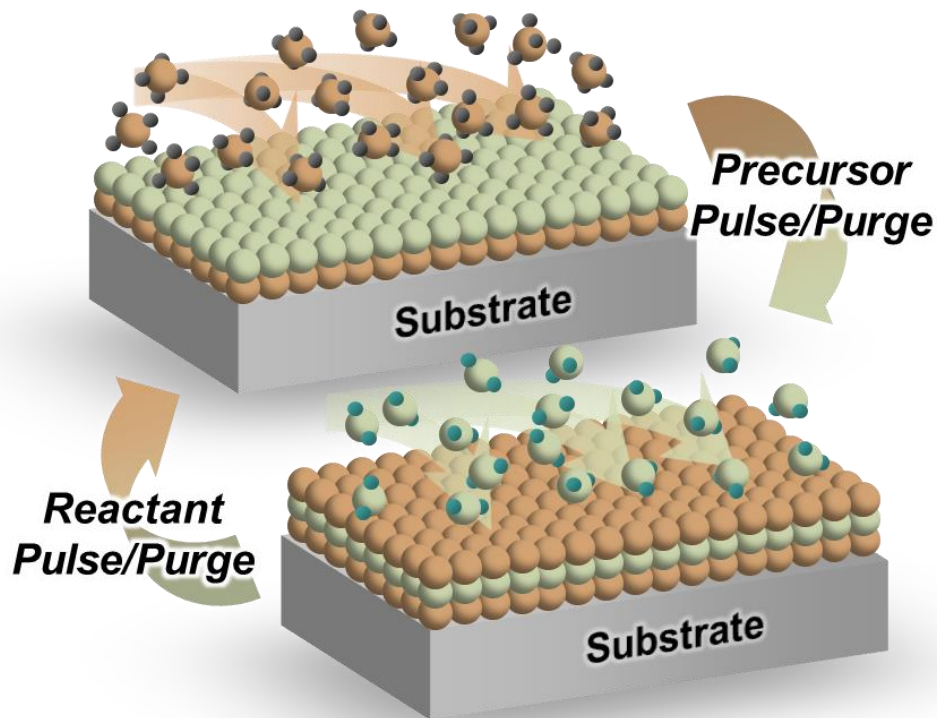
=> Relatively **long process** time
=> **low throughputs**
=> **Excess use** of precursors and reactants
- If non-ideal ALD process is performed, then the thin film quality would be pretty different from what you expect (potentially not desirable)
- ML for Autonomous ALD Process



Background and motivation

Atomic layer deposition (ALD)

Atomic Layer Deposition (ALD)



Angstrom ($\text{\AA}$)-scaled controllability

ALD Process Parameters

Precursor Pulse Time

Precursor Purge Time

Reactant Pulse Time

Reactant Purge Time

Cycle Number

Deposition Temperature

Precursor Temperature

Precursor Sources

Reactant Sources

Sample Locations

Reaction Chamber

Plasma or Thermal

Purging Gas

Flow Tube Reaction

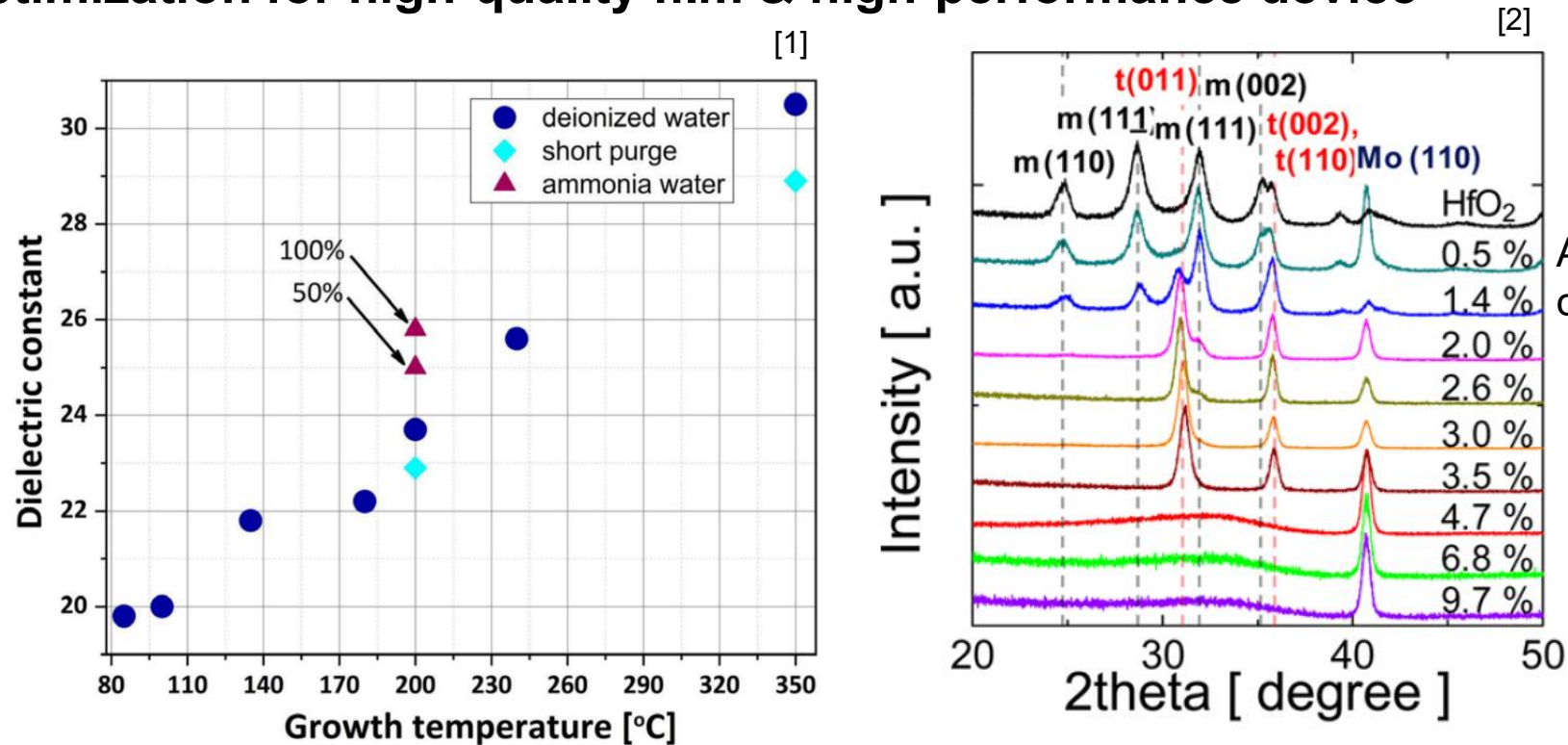
Pumping Capacity

Working Pressure

Gas Line Length

Reaction Substrate

■ Process Optimization for high-quality film & high-performance device



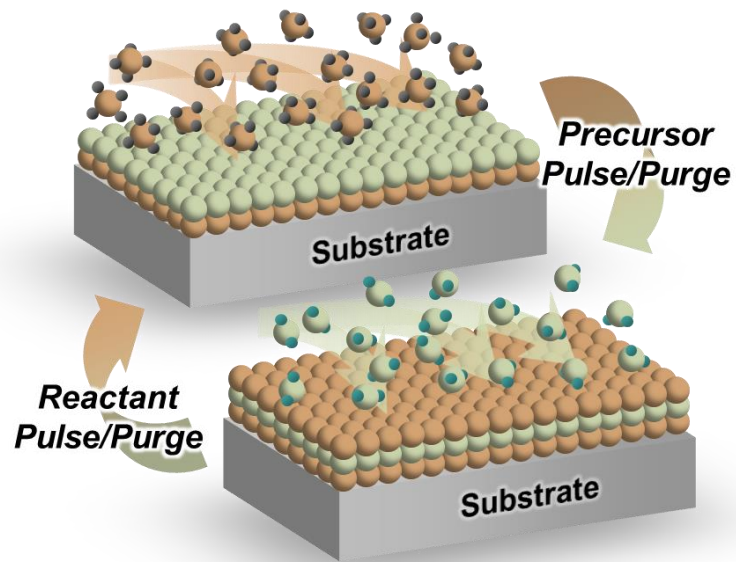
The deposition profile in ALD directly influences film quality and electrical performance

Background and motivation

Emerging 3D structure

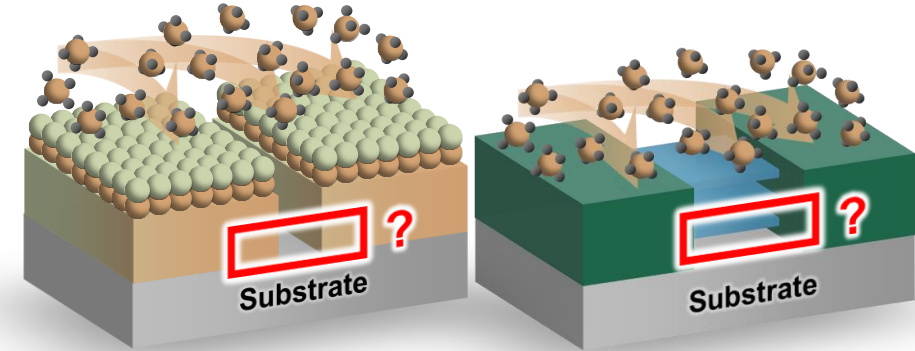
Complex Process Steps of Current ALD Technologies

Conventional 2D planar structure



Simply growing thin film
on 2D planar structure

More complex 3D structures have been emerged



Monitoring 3D structures
is even more complex to be predicted

**Deeper understanding
and analysis is necessary**



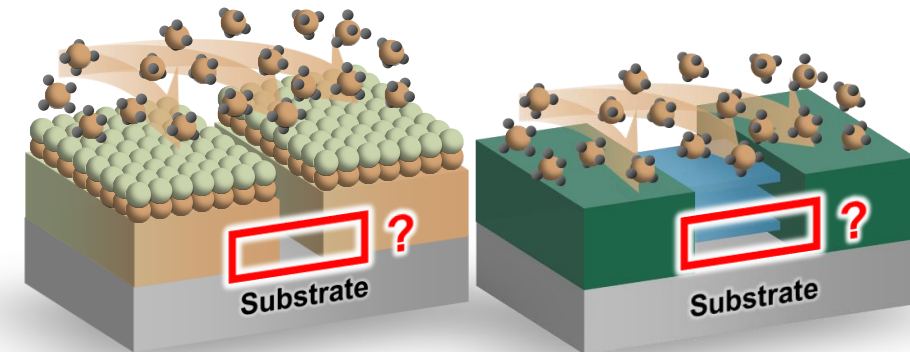
Background and motivation

Machine learning (ML) for ALD

Many ALD parameters must be optimized to achieve **high-quality films** and, ultimately, **high performance device**

ALD Process Parameters	
Precursor Pulse Time	Sample Locations
Precursor Purge Time	Reaction Chamber
Reactant Pulse Time	Plasma or Thermal
Reactant Purge Time	Purging Gas
Cycle Number	Flow Tube Reaction
Deposition Temperature	Pumping Capacity
Precursor Temperature	Working Pressure
Precursor Sources	Gas Line Length
Reactant Sources	Reaction Substrate

In **3D structures**, it is **difficult to know what occurs deep inside** the features, highlighting the need for deeper structural analysis and understanding.



Machine learning (ML) offers a powerful tool to interpret ALD behavior and extract insights from complex process data

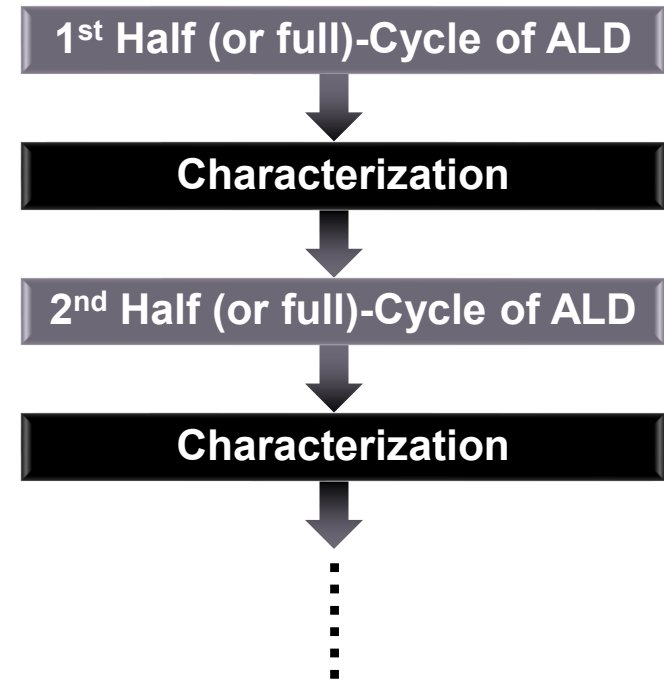
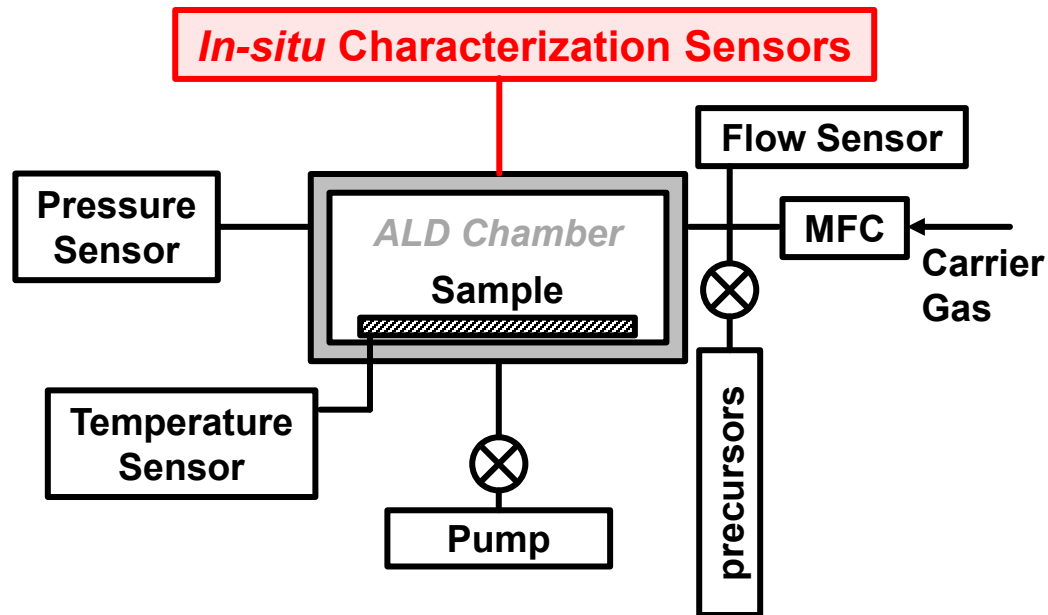


Background and motivation

Machine learning (ML) for ALD

In-situ ALD process

To achieve “**self-feedback ML-driven ALD system**,” the *in-situ* monitoring is helpful



***Economically & Efficiently
unfeasible!***

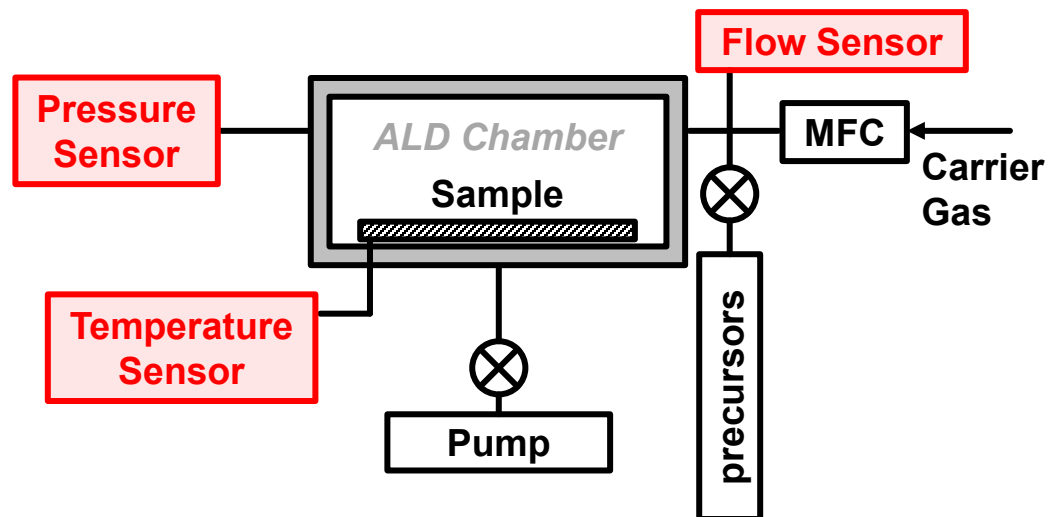


Our Approach

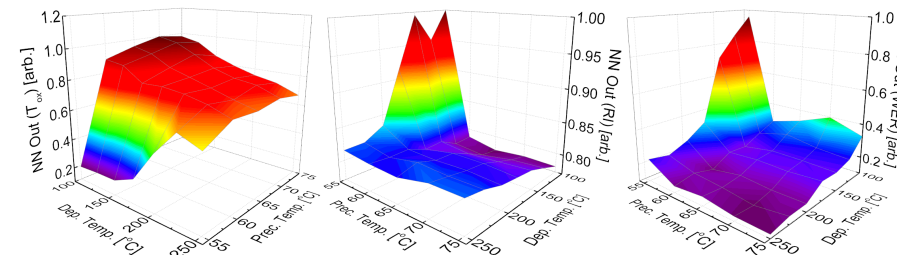
Proof-of-concepts for ML-driven ALD processes

“Pipeline” framework for autonomous ALD tool

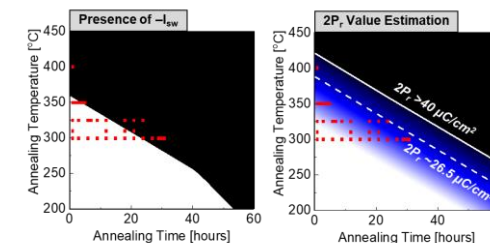
Self-feedback ML-driven ALD system, **by using the conventional process sensors** (e.g., pressure, temp.)



Film Property Models



Electrical Performance Models



Training ALD Tools



**Self-Feedback
During ALD**

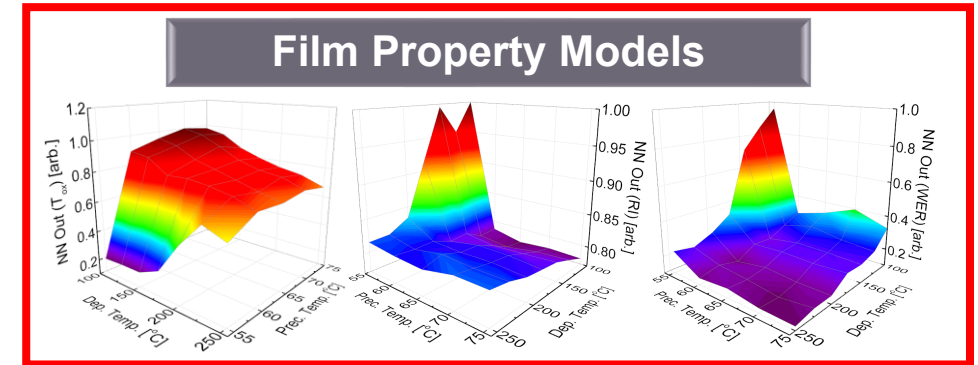
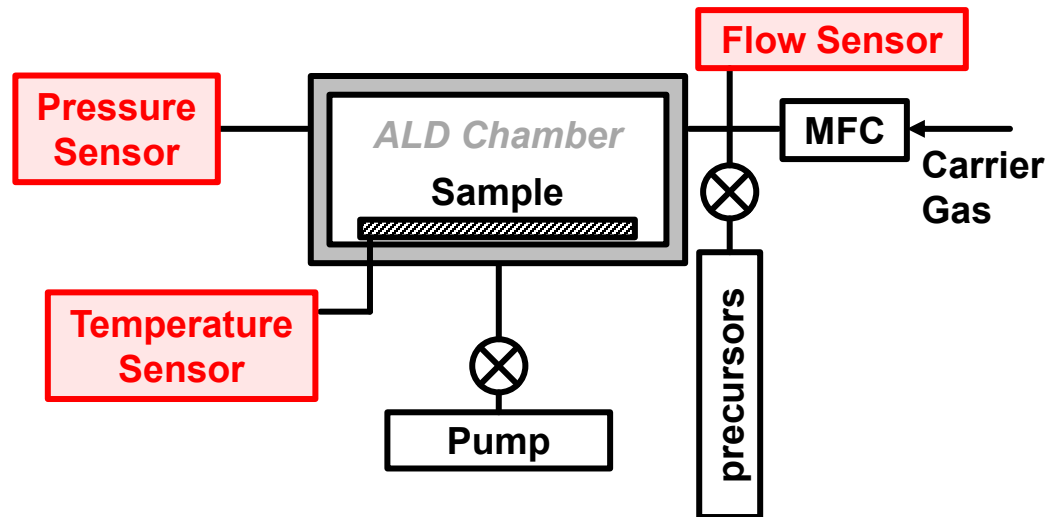


Our Approach

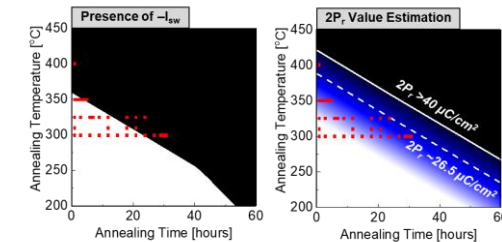
Proof-of-concepts for ML-driven ALD processes

“Pipeline” framework for autonomous ALD tool

Self-feedback ML-driven ALD system, by using the conventional process sensors (e.g., pressure, temp.)



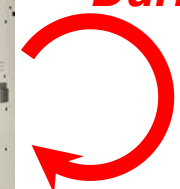
Electrical Performance Models



Training ALD Tools



**Self-Feedback
During ALD**

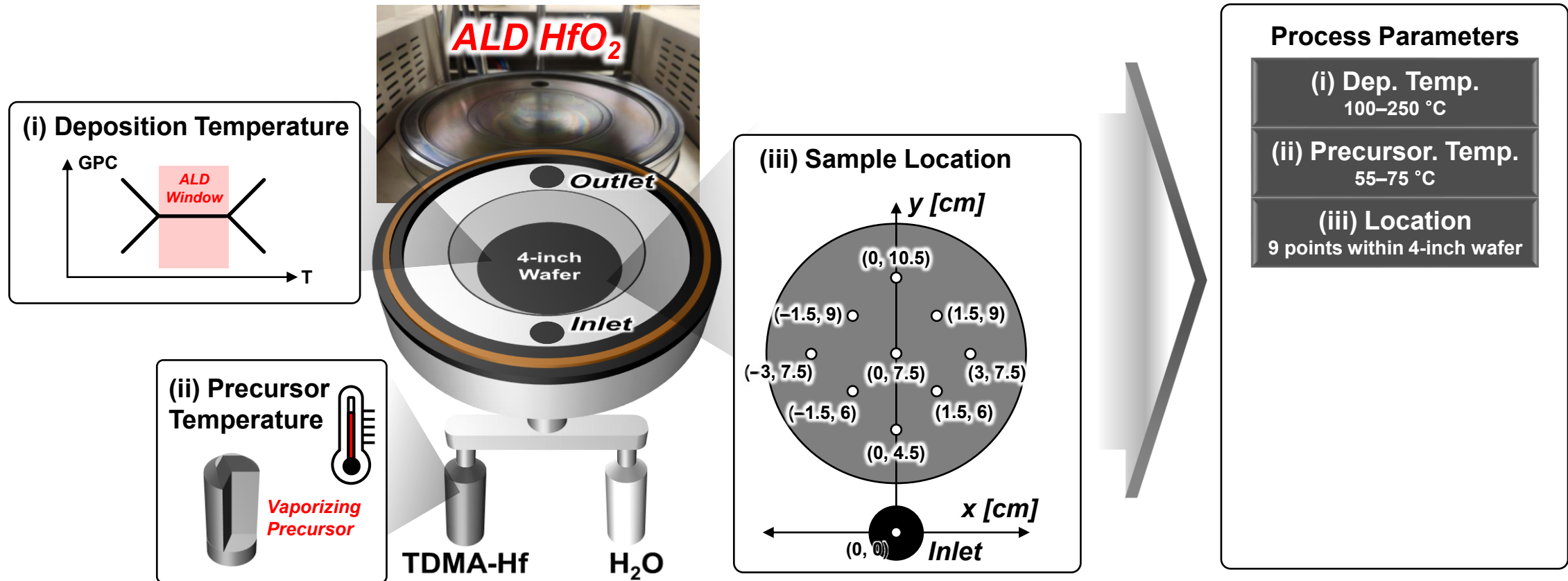




ML-Driven ALD Processes

Case studies of hafnium oxide growth on silicon substrate

■ Process variations and film properties of interest



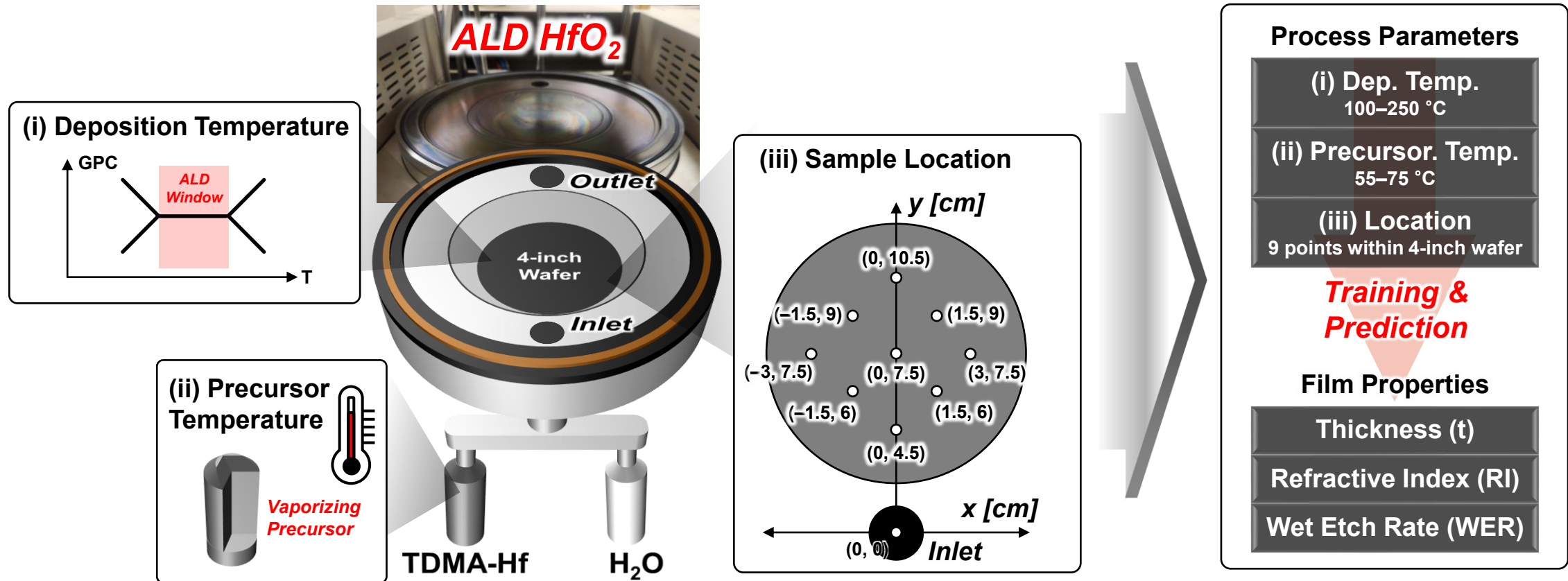
Three ALD parameters were controlled:
Deposition temp., precursor temp., sample location



ML-Driven ALD Processes

Case studies of hafnium oxide growth on silicon substrate

■ Process variations and film properties of interest



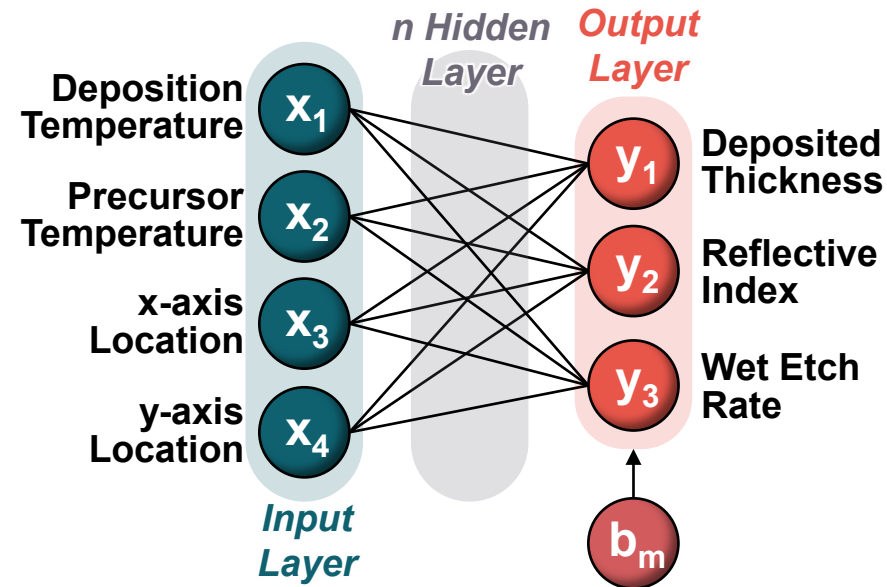
Three ALD parameters were controlled:
Deposition temp., precursor temp., sample location



ML-Driven ALD Processes

ML-driven ALD process workflow

■ Deep Neural Network (DNN)



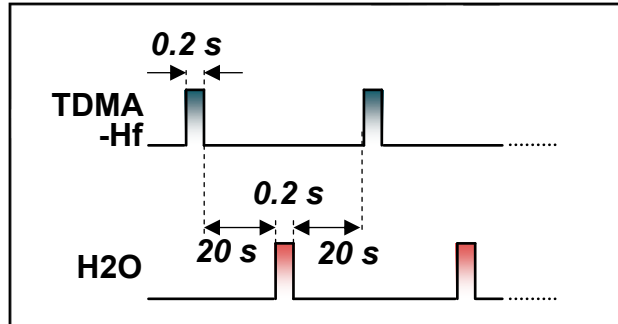


ML-Driven ALD Processes

ML-driven ALD process workflow

Deep Neural Network (DNN)

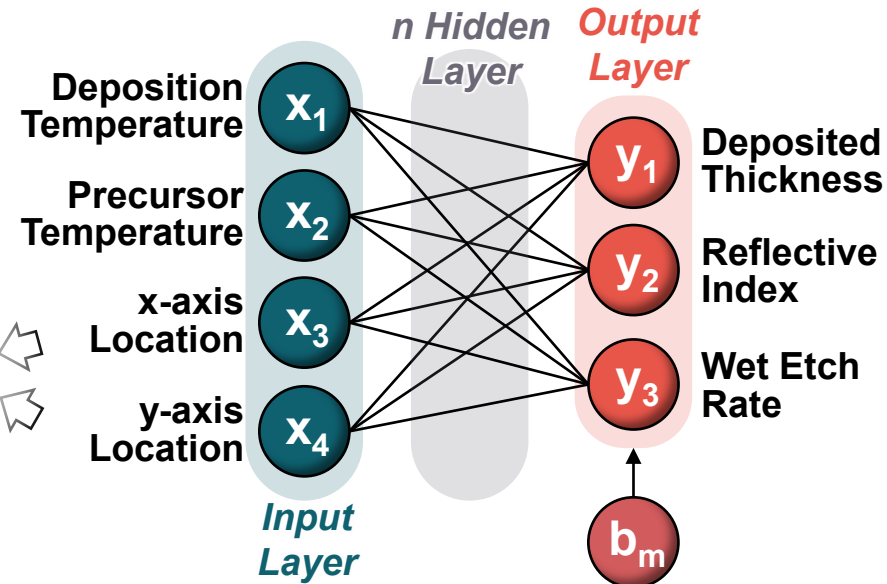
Working Pressure = ~310 mTorr
Ar Carrier Gas Flow = 40 sccm
Cycle # = 100 cycles



100–250 °C
(25 °C step)

55–75 °C
(5 °C step)

9 Points
over 4" Wafer



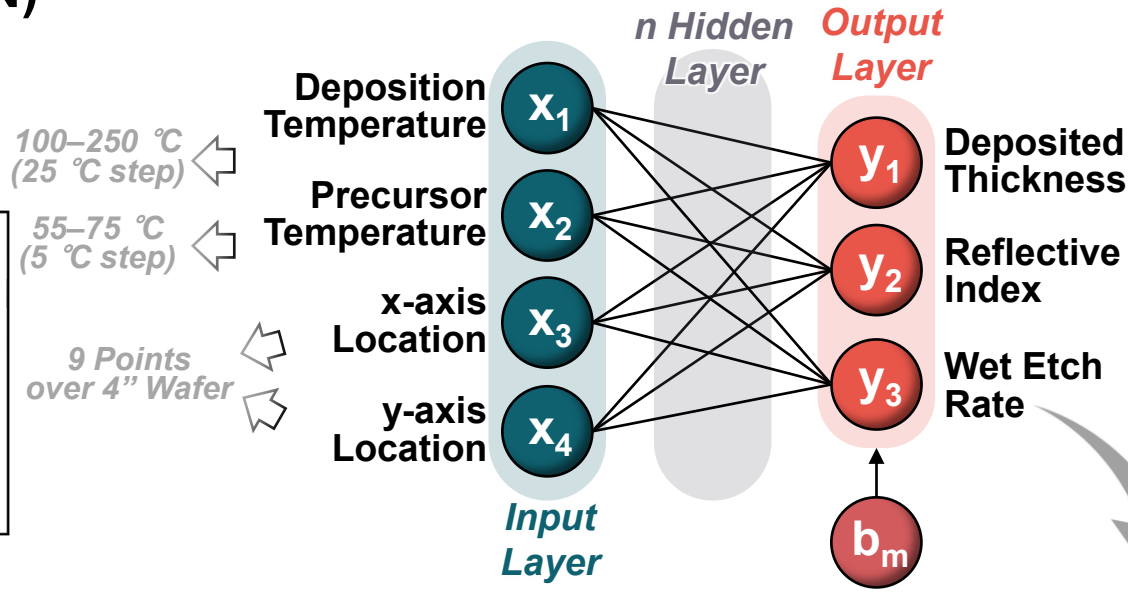
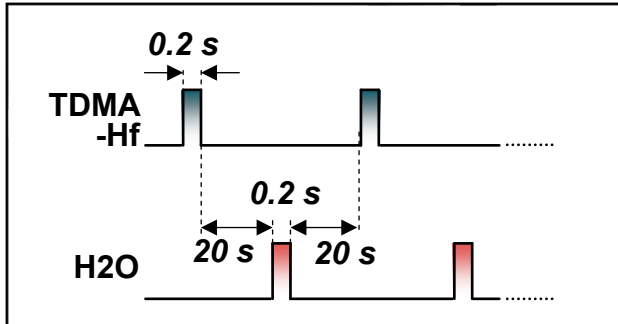


ML-Driven ALD Processes

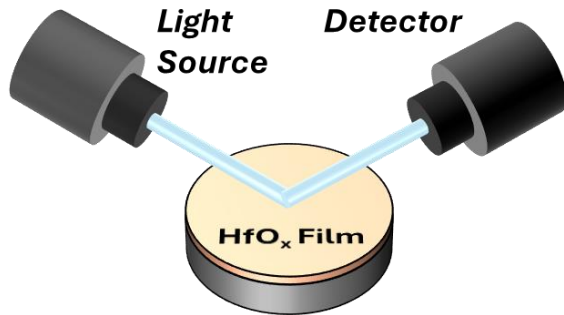
ML-driven ALD process workflow

Deep Neural Network (DNN)

Working Pressure = ~310 mTorr
Ar Carrier Gas Flow = 40 sccm
Cycle # = 100 cycles

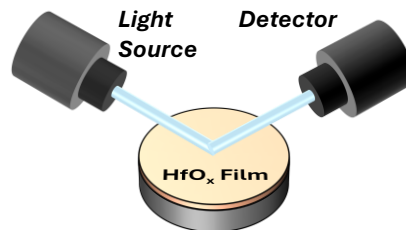


Ellipsometry for T_{ox} & RI

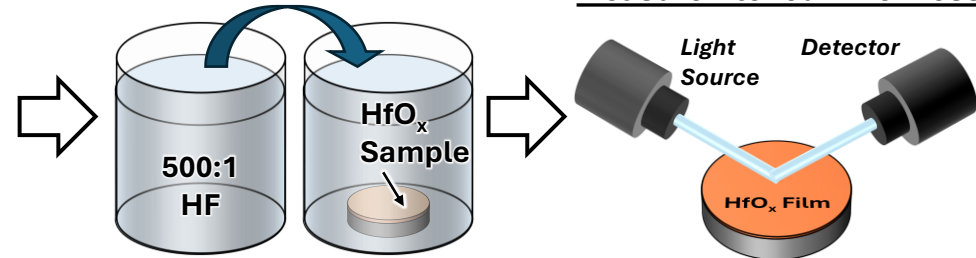


500:1 HF Etchant for 1 or 5 min (Wet Etch Rate Test)

Measure Initial Thickness



Measure Etched Thickness



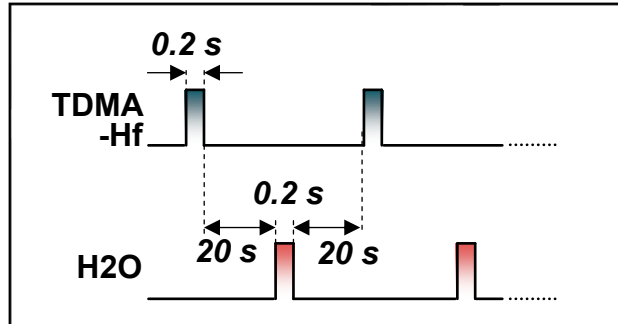


ML-Driven ALD Processes

ML-driven ALD process workflow

Deep Neural Network (DNN)

Working Pressure = ~310 mTorr
Ar Carrier Gas Flow = 40 sccm
Cycle # = 100 cycles



100–250 °C
(25 °C step)

55–75 °C
(5 °C step)

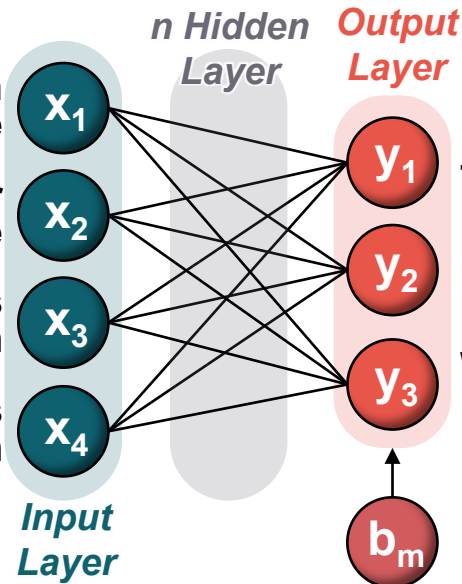
9 Points
over 4" Wafer

Deposition
Temperature

Precursor
Temperature

x-axis
Location

y-axis
Location

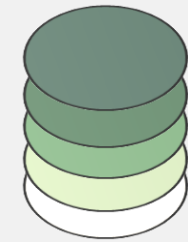


Deposited
Thickness

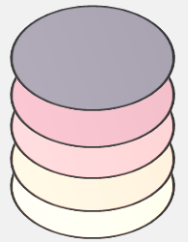
Reflective
Index

Wet Etch
Rate

Training Set
(215 data)

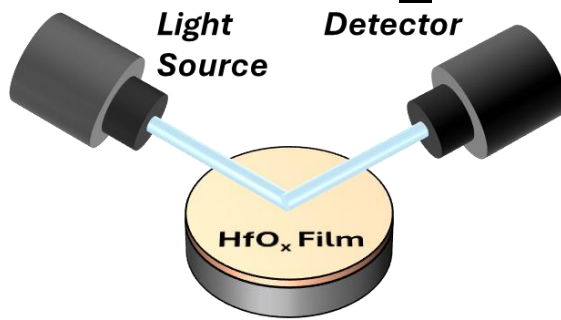


Test Set
(100 data)



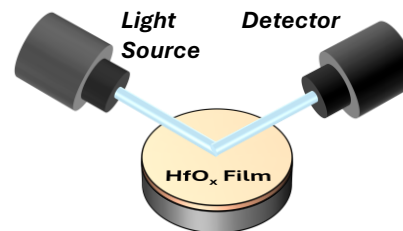
Total 315
datapoints

Ellipsometry for T_{ox} & RI

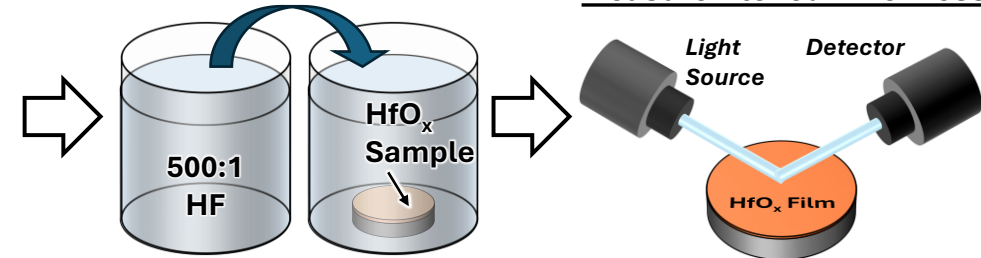


500:1 HF Etchant for 1 or 5 min (Wet Etch Rate Test)

Measure Initial Thickness



Measure Etched Thickness

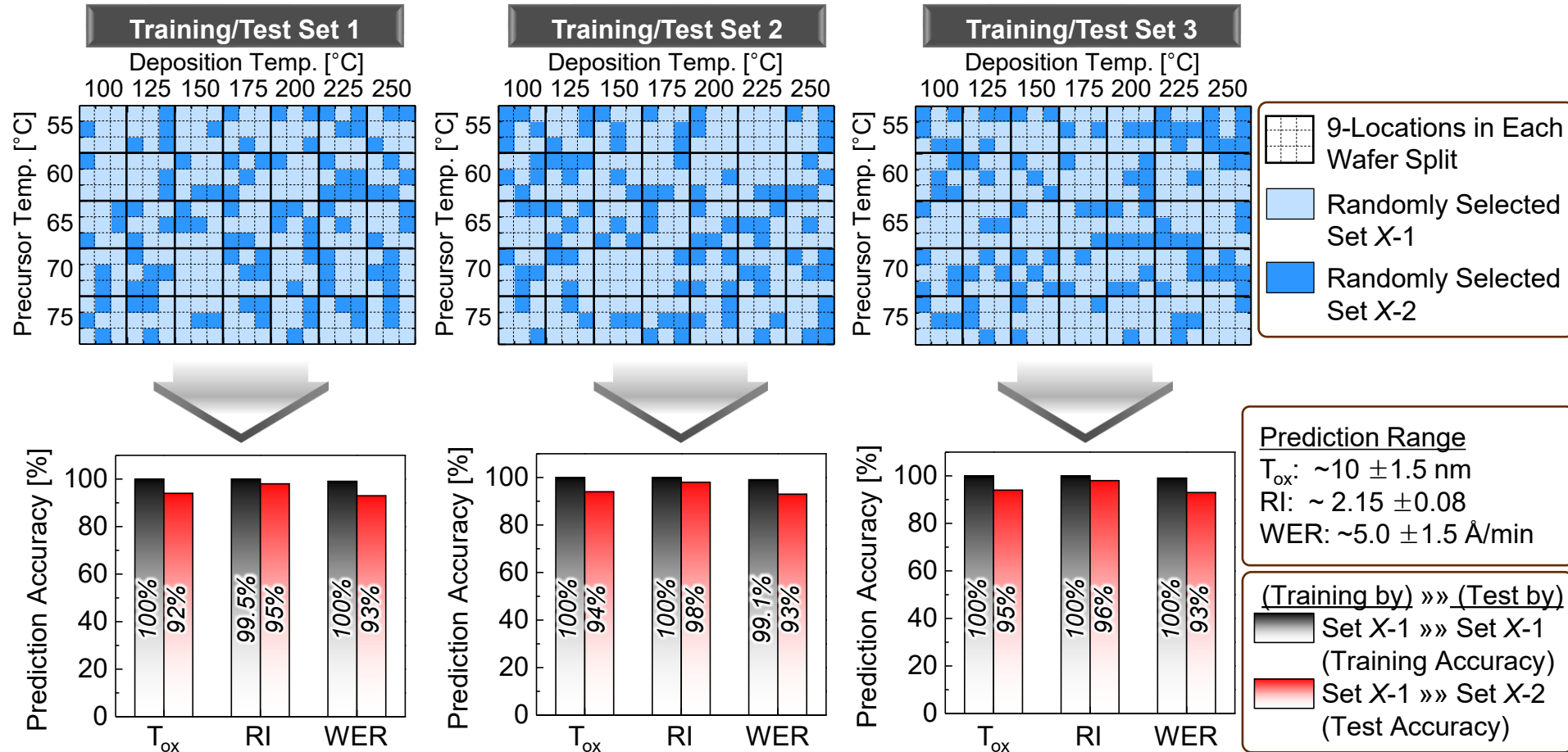




ML-Driven ALD Processes

Predictive work using ML

Prediction accuracy



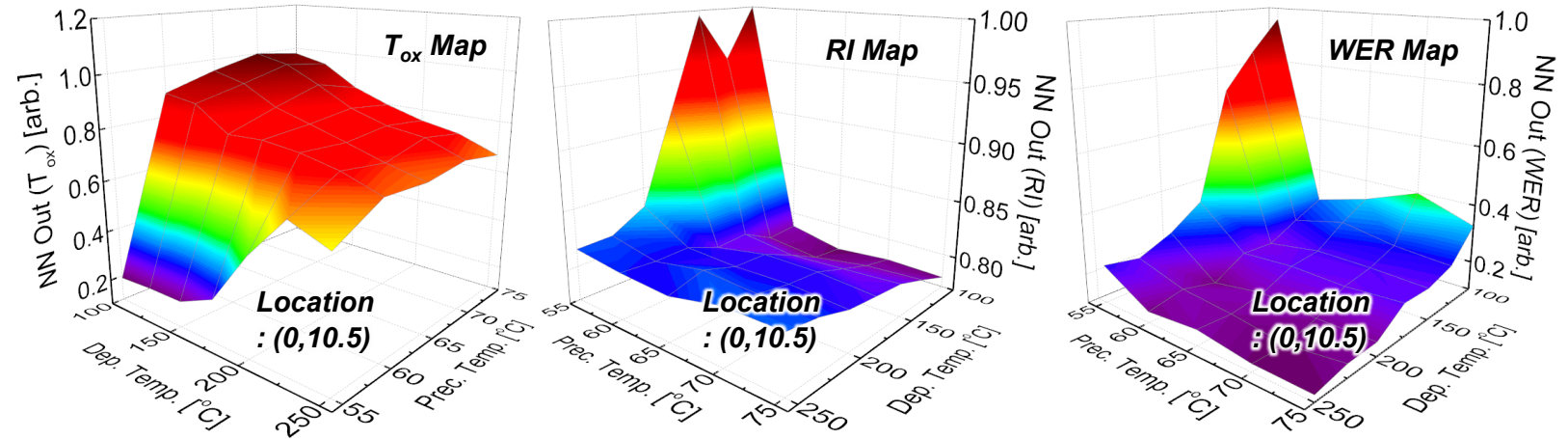


ML-Driven ALD Processes

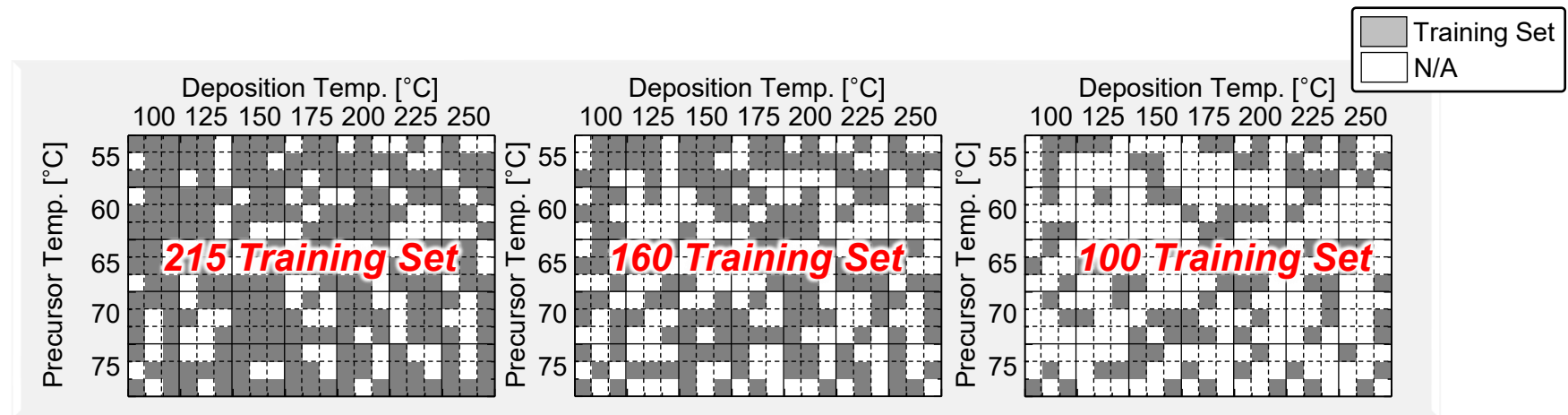
ALD prediction maps

Prediction maps

Physical Space
**Experimental
Map**



Virtual Space
**Prediction
Map**



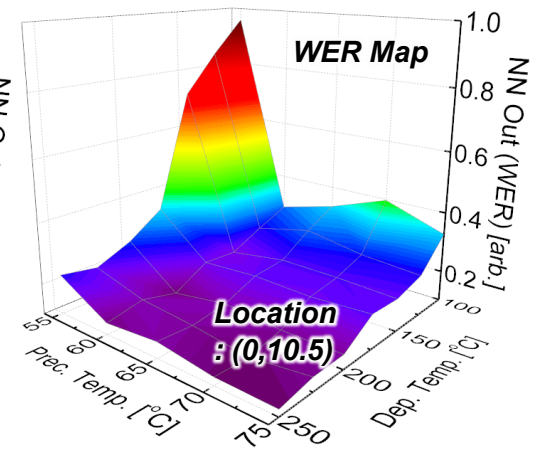
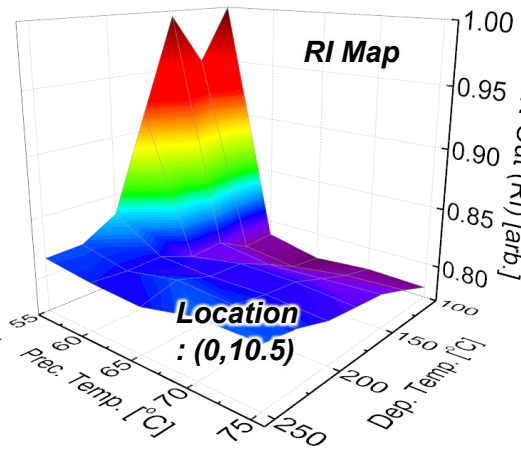
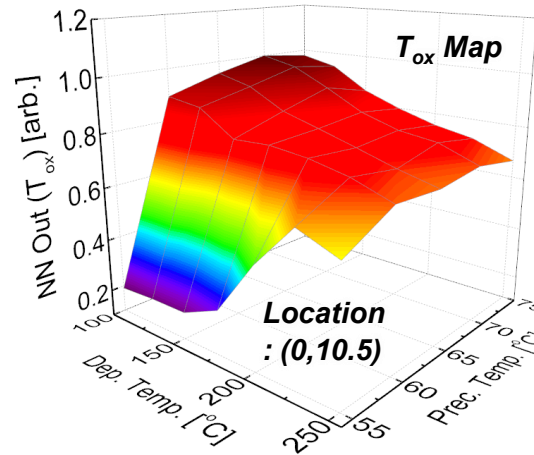


ML-Driven ALD Processes

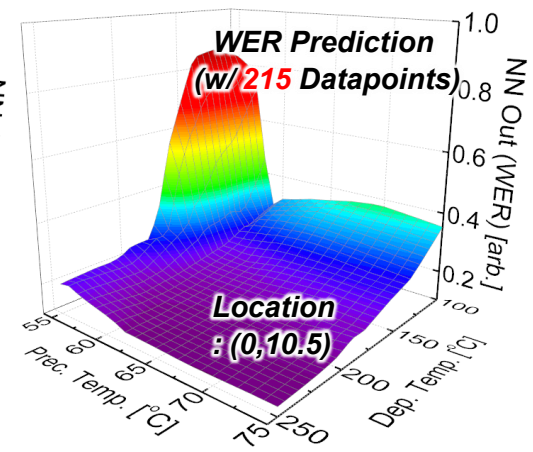
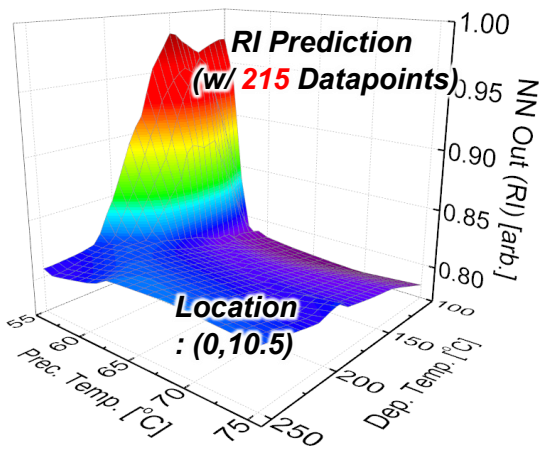
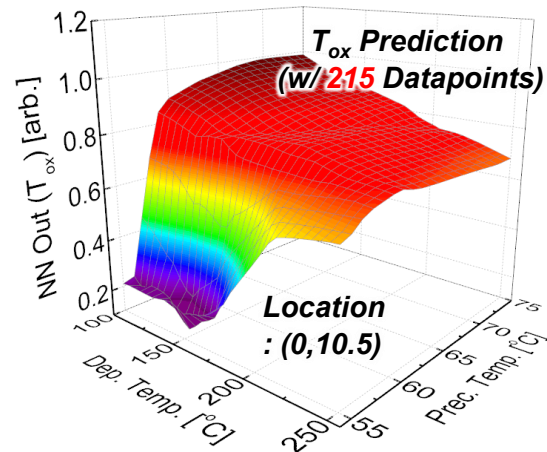
ALD prediction maps w/ 215 datapoints

Prediction maps

Physical Space
**Experimental
Map**



Virtual Space
**Prediction
Map**



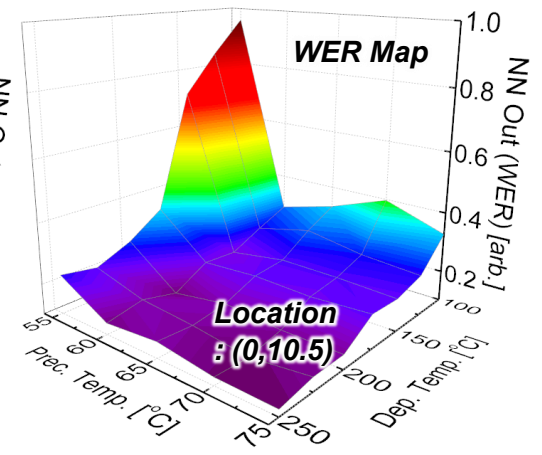
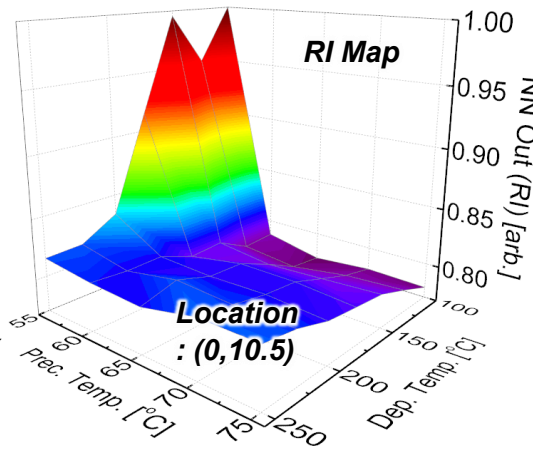
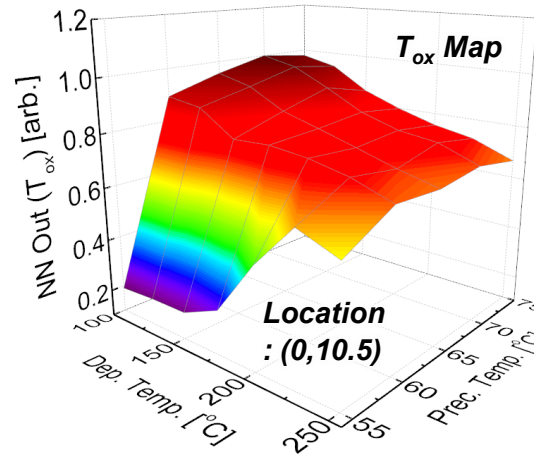


ML-Driven ALD Processes

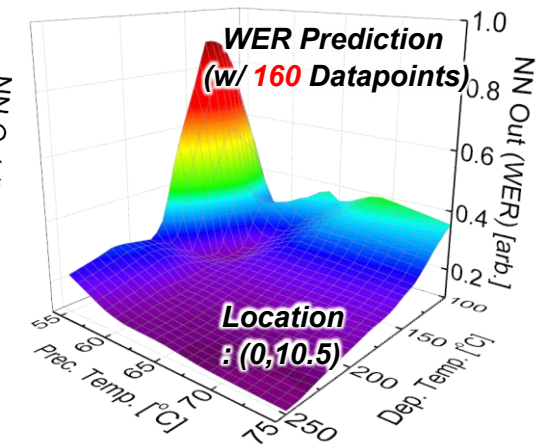
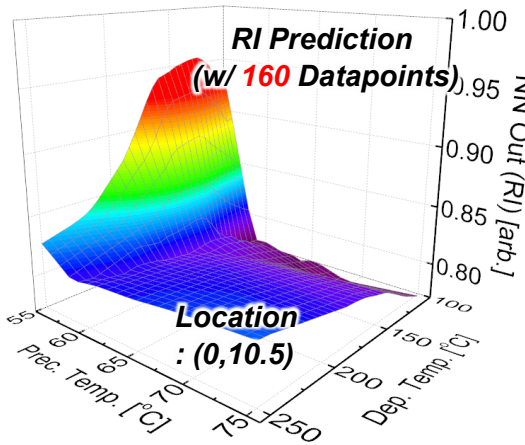
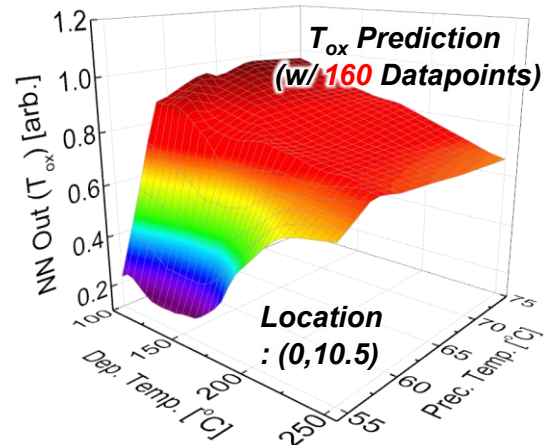
ALD prediction maps w/ 160 datapoints

Prediction maps

Physical Space
**Experimental
Map**



Virtual Space
**Prediction
Map**



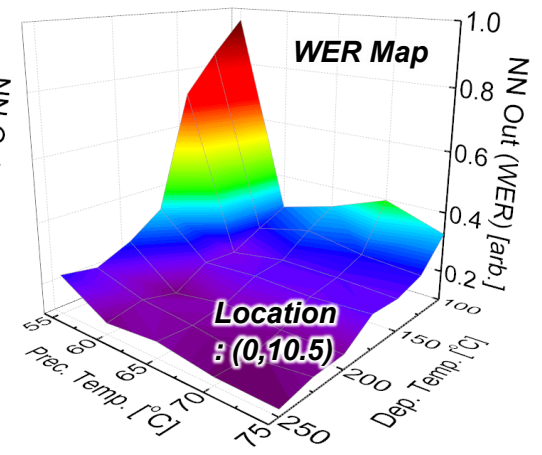
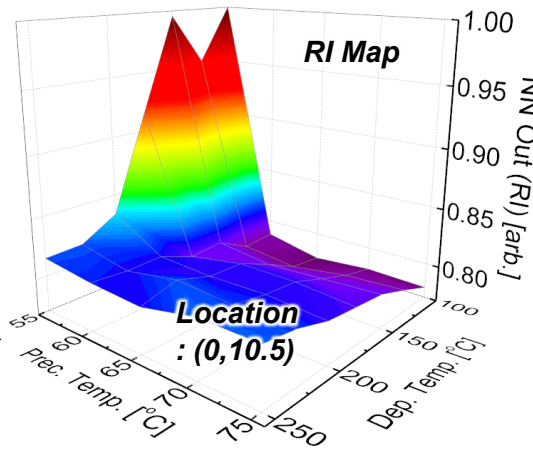
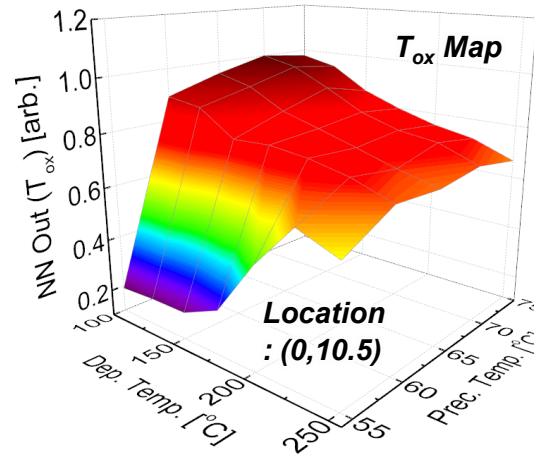


ML-Driven ALD Processes

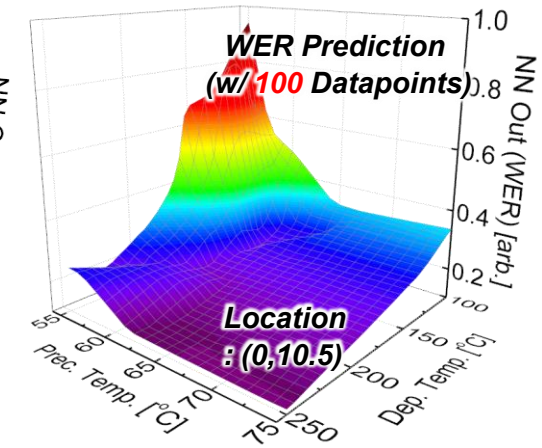
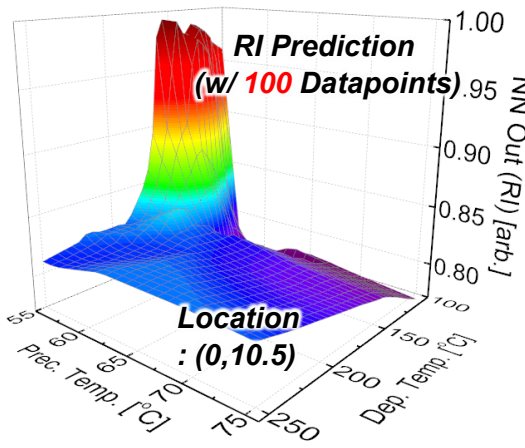
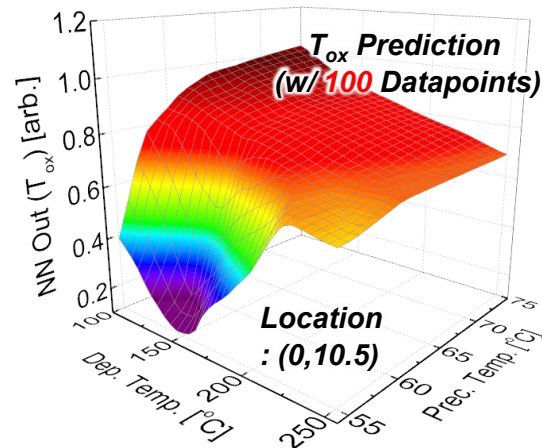
ALD prediction maps w/ 100 datapoints

Prediction maps

Physical Space
**Experimental
Map**



Virtual Space
**Prediction
Map**

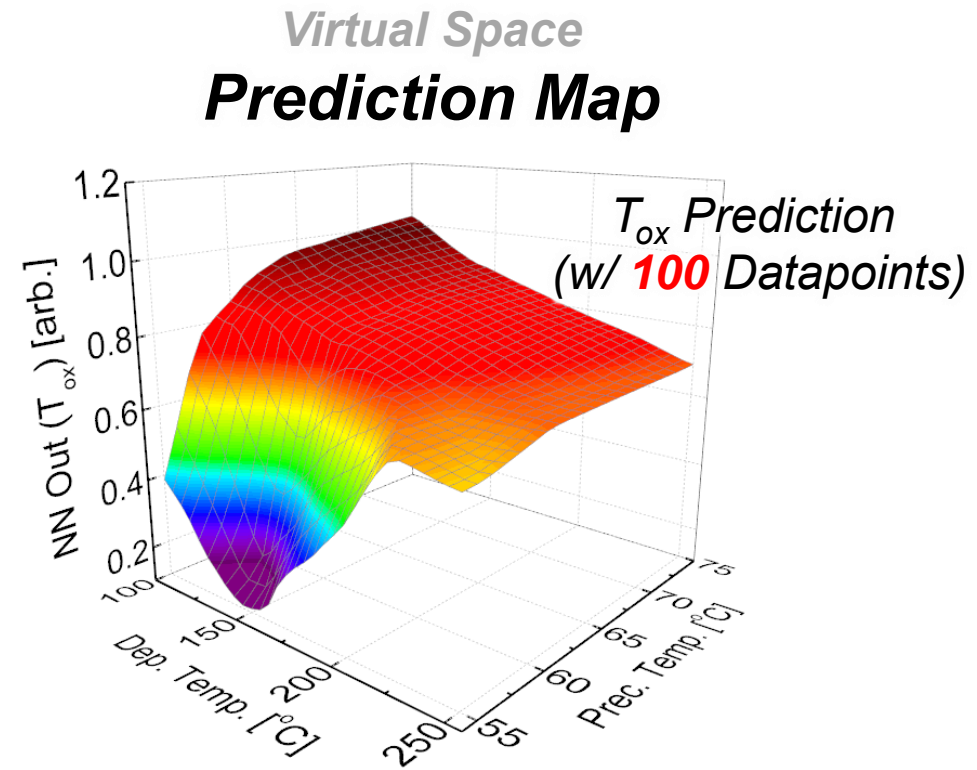
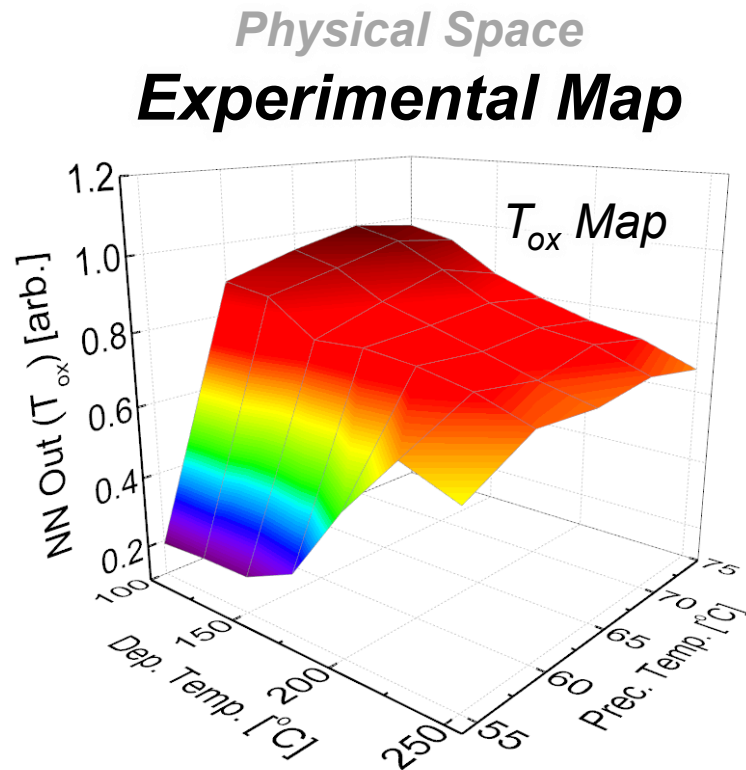




ML-Driven ALD Processes

ALD prediction maps

Prediction maps



The prediction map successfully captures the growth trend as a function of deposition and precursor temperatures



ML-Driven ALD Processes

ALD prediction maps

Extended prediction maps
(ML-based trained map w/ 100 datapoints)

Precursor Temperature:
55 °C – 75 °C

Deposition Temperature:
100 °C – 250 °C



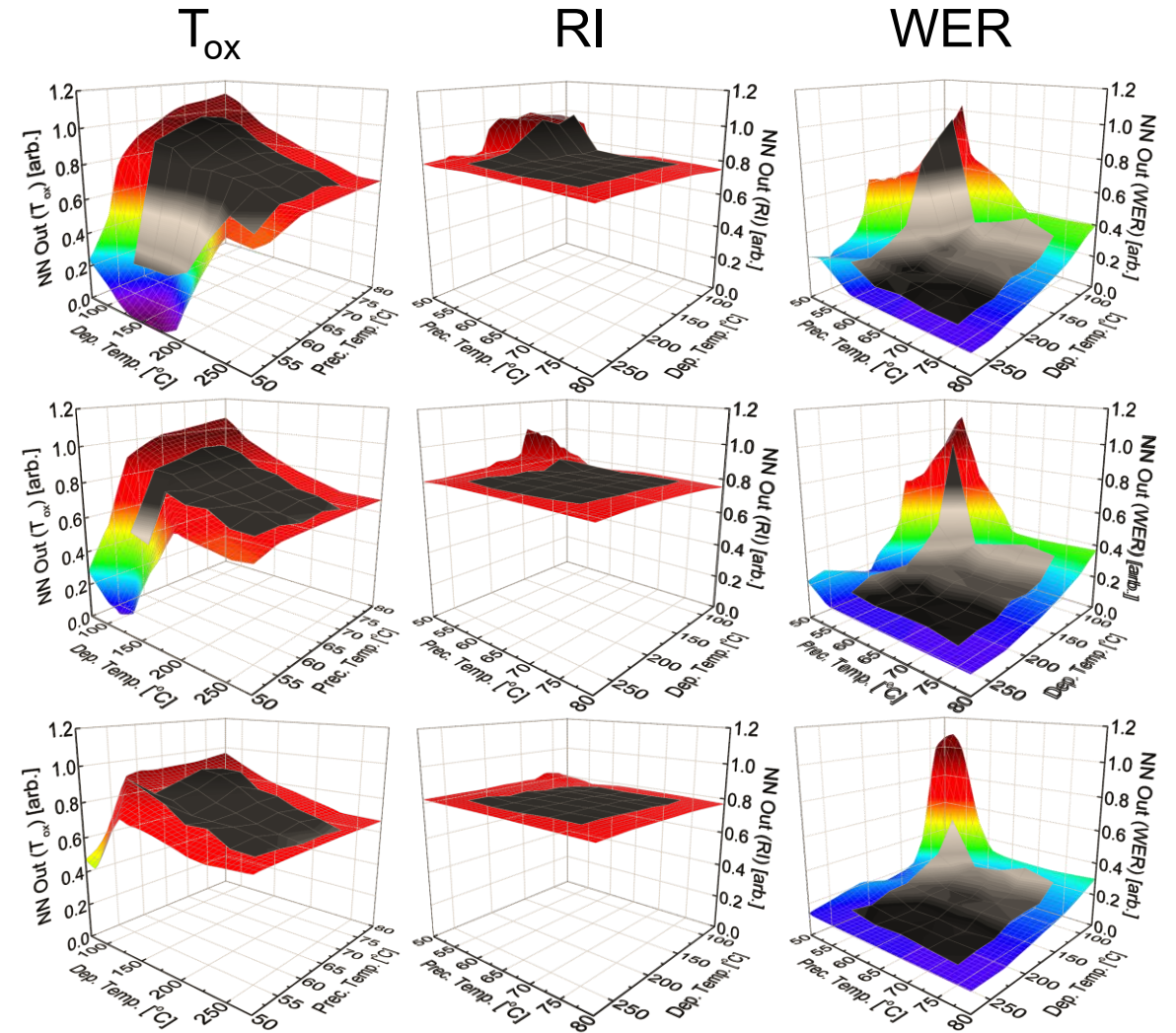
Precursor Temperature:
50 °C – 80 °C

Deposition Temperature:
75 °C – 275 °C

$(x, y) = (0, 10.5)$

$(x, y) = (0, 7.5)$

$(x, y) = (0, 4.5)$





ML-Driven ALD Processes

ALD prediction maps

Extended prediction maps
(ML-based trained map w/ 100 datapoints)

Precursor Temperature:
55 °C – 75 °C

Deposition Temperature:
100 °C – 250 °C



Precursor Temperature:

50 °C – 80 °C

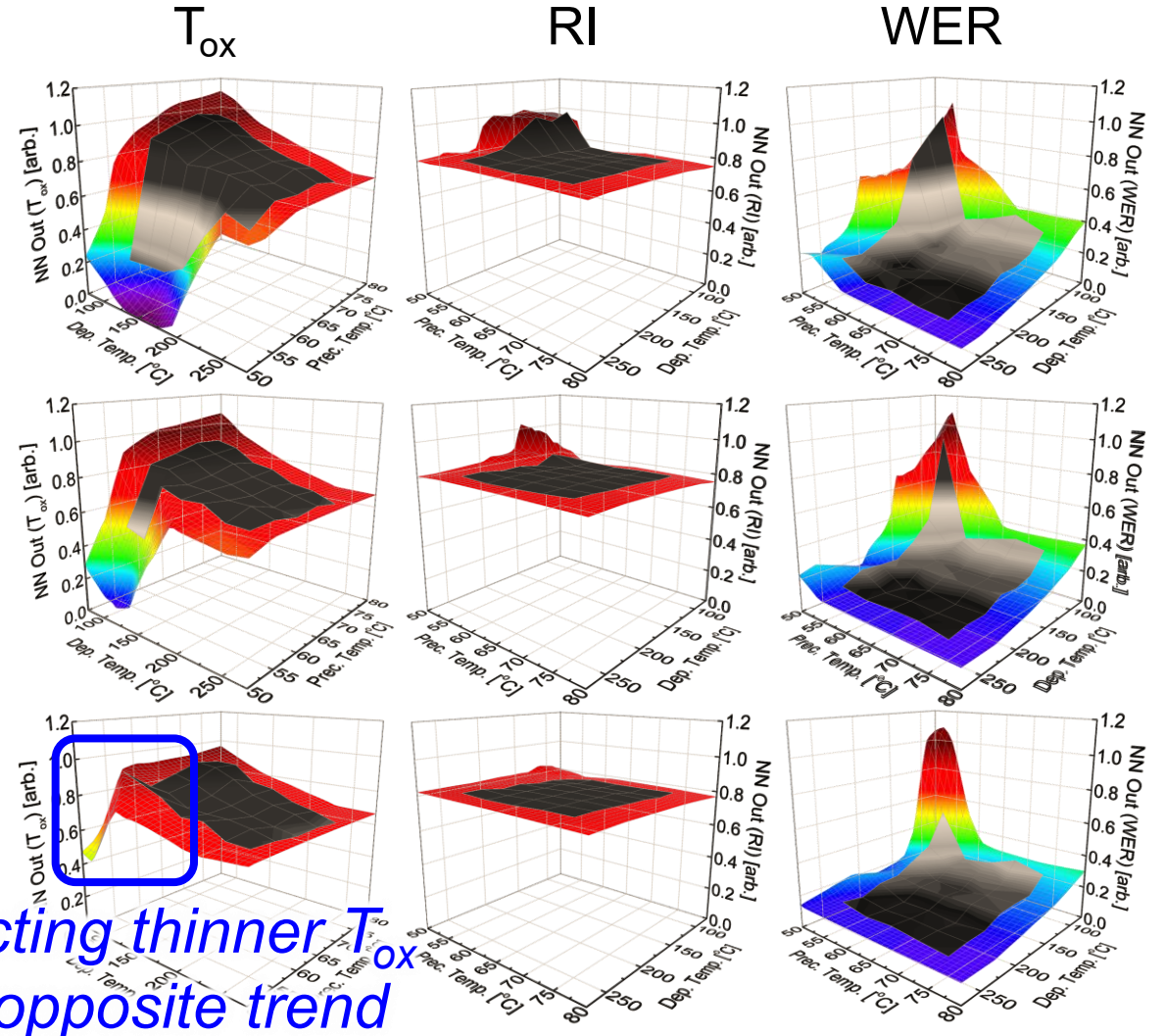
Deposition Temperature:
75 °C – 275 °C

$(x, y) = (0, 10.5)$

$(x, y) = (0, 7.5)$

$(x, y) = (0, 4.5)$

*Predicting thinner T_{ox}
with opposite trend*





ML-Driven ALD Processes

ALD prediction maps

Extended prediction maps
(ML-based trained map w/ 100 datapoints)

Precursor Temperature:
55 °C – 75 °C

Deposition Temperature:
100 °C – 250 °C



Precursor Temperature:
50 °C – 80 °C

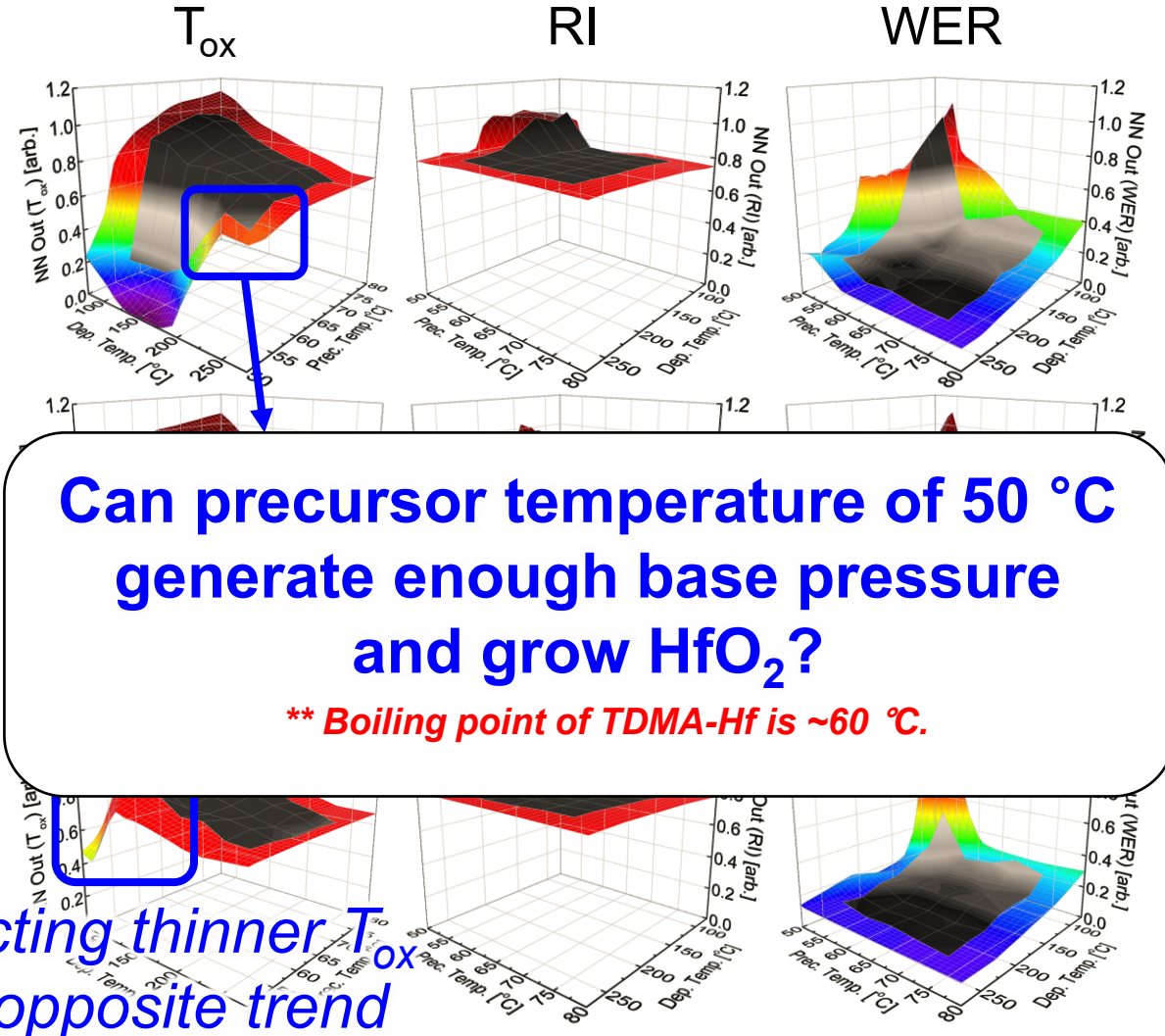
Deposition Temperature:
75 °C – 275 °C

$(x, y) = (0, 10.5)$

$(x, y) = (0, 7.5)$

$(x, y) = (0, 4.5)$

Predicting thinner T_{ox}
with opposite trend



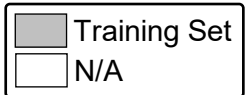
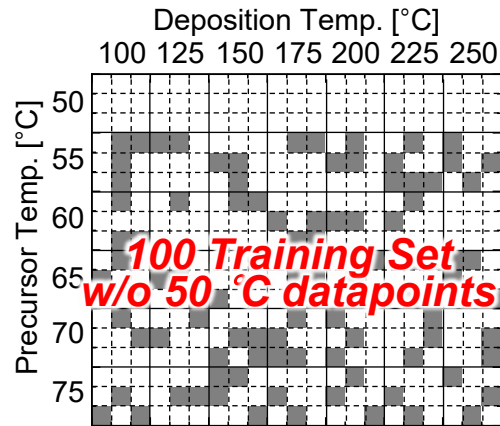


ML-Driven ALD Processes

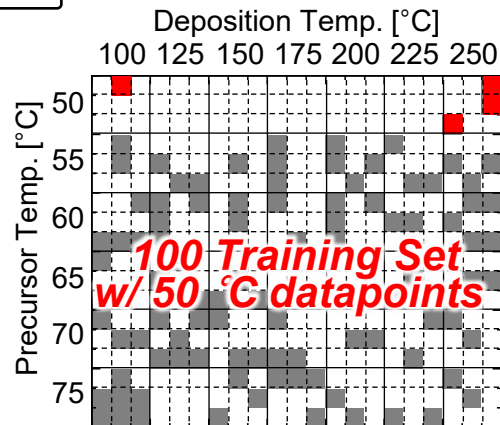
ALD prediction maps

■ Include 50 °C training data

w/o 50 °C
datapoints



w 50 °C
datapoints



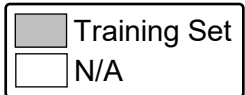
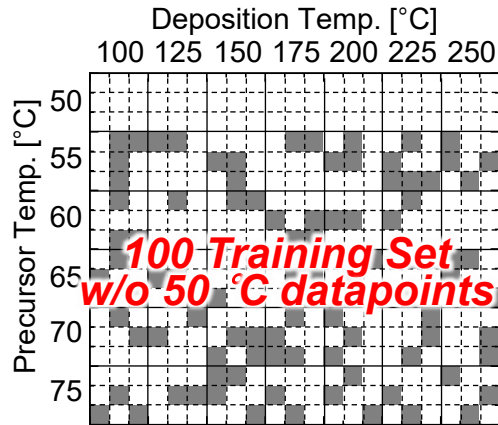


ML-Driven ALD Processes

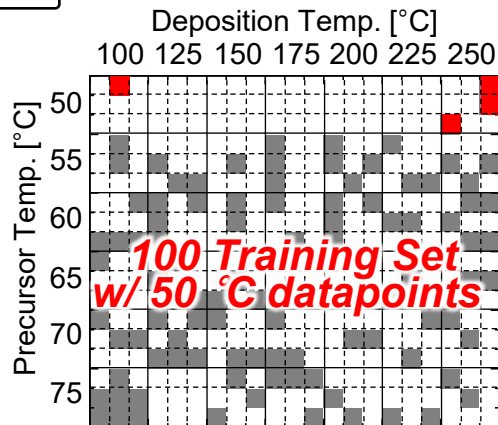
ALD prediction maps

■ Include 50 °C training data

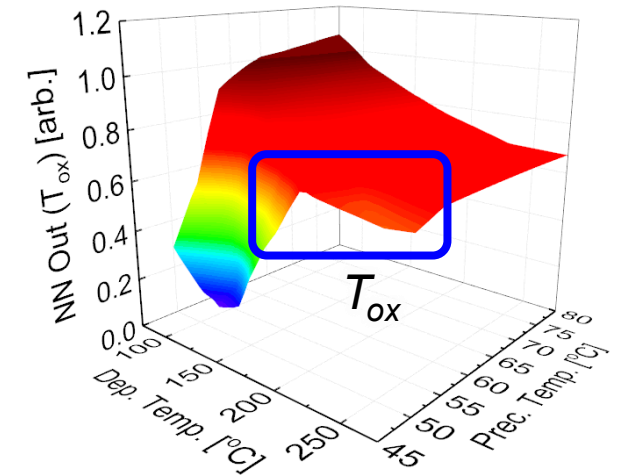
w/o 50 °C
datapoints



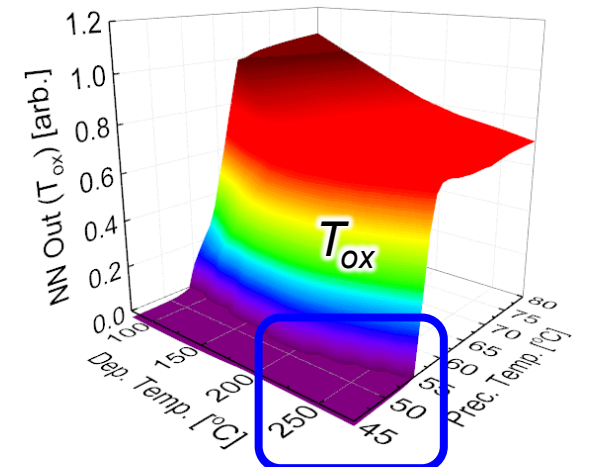
w 50 °C
datapoints



Precursor Temperature:
50 °C – 80 °C
Deposition Temperature:
75 °C – 275 °C



Precursor Temperature:
45 °C – 80 °C
Deposition Temperature:
75 °C – 275 °C





Summary

❑ Machine learning (ML) can offer a powerful tool to interpret ALD behavior and extract insights from complex process data

- ✓ Many ALD parameters needed to be controlled for process optimization
- ✓ Deeper understanding for 3D structures
- ✓ “Pipeline research” on how we can apply machine learning to ALD process efficiently

❑ ML-driven ALD processes using DNN systems

- ✓ Apply ML to the ALD process through the use of process parameters as inputs and prediction of film properties as outputs
- ✓ Assess the required number of training datapoints
- ✓ Demonstrate the advantages of machine learning, particularly in enabling broader exploration of the process parameter space
- ✓ Including poor or failed results in training data is critical for improving the accuracy of ML predictions

❑ ***In-operando* Auto-Reprogramming Process based on ML Predictions**

- ✓ In-operando measurements big-data sets enable to predict the film qualities/properties using ML
- ✓ Training the tool that can modify process parameters to obtain the expected target results *during the process*
- ✓ Eventually, add 3D process and characteristics capabilities for advanced semiconductor processing

❑ **Even Further Predictions on Device Electrical/Reliability Characteristics**

❑ **Autonomous ALD process to enhance manufacturing capabilities and the thin film qualities**

Thank you



Questions?
Email to
Jiyoung.Kim@utdallas.edu